

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL10B182JB8NNNC**
- Description : **CAP, 1.8nF, 50V, ±5%, X7R, 0603**

A. Samsung Part Number

CL 10 B 182 J B 8 N N N C
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor									
② Size	0603 (inch code)	L: 1.6	±0.1	mm	W: 0.8	±0.1	mm			
③ Dielectric	X7R	⑧ Inner electrode	Ni							
④ Capacitance	1.8 nF	Termination	Cu							
⑤ Capacitance tolerance	±5 %	Plating	Sn 100% (Pb Free)							
⑥ Rated Voltage	50 V	⑨ Product	Normal							
⑦ Thickness	0.8 ±0.1 mm	⑩ Special	Reserved for future use							
		⑪ Packaging	Cardboard Type, 7" reel							

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms
Tan δ (DF)	0.025 max.	
Insulation Resistance	10,000Mohm or 500Mohm·uF Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	X7R (From -55℃ to 125℃, Capacitance change should be within ±15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 95% of terminal surface is to be soldered newly	1) Sn63Pb37 solder 235±5℃, 5±0.5sec. 2) SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±7.5% Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
Humidity	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.05 max IR : 1000Mohm or 50Mohm $\cdot$ μ F Whichever is Smaller	40 $\pm$ 2 $^{\circ}$ C, 90~95%RH, 500+12/-0hrs
Moisture Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.05 max IR : 500Mohm or 25Mohm $\cdot$ μ F Whichever is Smaller	With rated voltage 40 $\pm$ 2 $^{\circ}$ C, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.05 max IR : 1000Mohm or 50Mohm $\cdot$ μ F Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within $\pm 7.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow$ 25 $^{\circ}$ C $\rightarrow$ Max. operating temperature $\rightarrow$ 25 $^{\circ}$ C 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 250 $\pm$ 5 $^{\circ}$ C, 6sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.